

VSML2512S3 Series, Current Sensor Resistor (Lead / Halogen Free)

Features / Applications :

- High power rating is up to 3W
- Welding construction; excellent long-term stability
- Automotive applications & Current Sensor Resistor
- Suggested mounting on DBC/IMS/FR4 substrate
- RoHS compliant and AEC Q200 qualified



Electrical Specifications:

Characteristics ¹	Feature
Power Rating ²	3 W
Resistance Value	0.3 to 10 m Ω
Temperature Coefficient of Resistance (25/125°C)	From 50 ppm/°C
Operation Temperature Range	-65°C∼ +170°C
Resistance Tolerance	± 1%
Maximum Working Voltage (V)	(P*R) ^{1/2}

- 1. For detail information refer to the table on page 3 P/N list
- 2. For resistors are operated at ambient temperature in excess of 70°C, the maximum load shall be derated in accordance with the following curve.

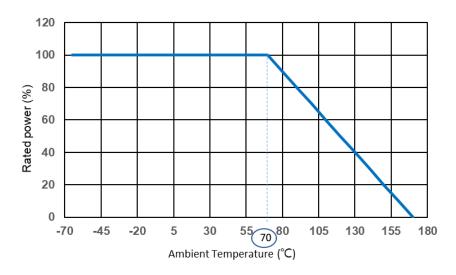


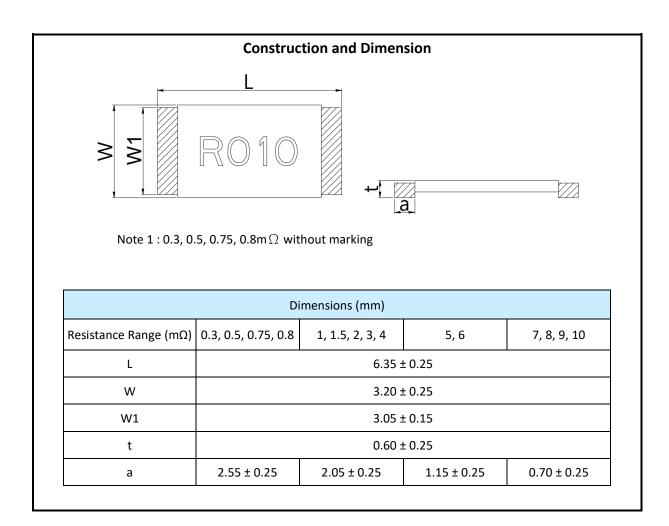
Figure 1. : Power derating curve at ambient temperature

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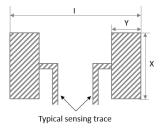
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Outline Drawing:



Recommended Solder Pad Dimensions



Resistance Range	Dimensions			
mΩ	X (mm) Y (mm) I (mm)			
0.3 to 4		3.2		
5 to 6	3.7	2.1	7.35	
7 to 10		1.65		

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Type Designation:

V S M L 2512 S - - - - - - (1) (2) (3) (4) (5) (6)

Note:

(1) Series No.

(2) Size

(3) Terminal Type : S = Short terminal

(4) Power Rating: 3 = 3W

(5) Resistance value : $R003 = 0.003\Omega$, $OM50 = 0.0005\Omega$

(6) Tolerance : $F = \pm 1\%$, $G = \pm 2\%$, $J = \pm 5\%$

P/N list:

D/N	R value	TCR	Power Rating		Tolerance	
P/N	(mΩ)	(ppm/K)	(W)	1%	2%	5%
VSML2512S3-0M30*	0.3	±125	3	✓		
VSML2512S3-0M50*	0.5	±100	3	✓		
VSML2512S3-0M75*	0.75	±100	3	✓		
VSML2512S3-0M80*	0.8	±100	3	✓		
VSML2512S3-R001*	1.0	±75	3	✓		
VSML2512S3-1M50*	1.5	±75	3	✓		
VSML2512S3-R002*	2.0	±75	3	✓		
VSML2512S3-R003*	3.0	±75	3	✓		
VSML2512S3-R004*	4.0	±75	3	✓		
VSML2512S3-R005*	5.0	±50	3	✓		
VSML2512S3-R006*	6.0	±50	3	✓		
VSML2512S3-R007*	7.0	±50	3	✓		
VSML2512S3-R008*	8.0	±50	3	✓		
VSML2512S3-R009*	9.0	±50	3	✓		
VSML2512S3-R010*	10.0	±50	3	✓		

^{*} Note : Other values and tolerance would be available, please contact Cyntec.

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Characteristics:

Electrical

Item	Specification and Requirement	Test Method
Temperature Coefficient (TCR)	As follow specification	JIS-C-5201 +25°C / +125°C
Short Time Overload	$\triangle R\colon\! \pm 0.5\%$ Without damage by flashover, spark, arcing, burning or breakdown	JIS-C-5201-1 4.13 2.5 x rated power for 5 seconds.
ESD	$\triangle R$: \pm 1% Without damage by flashover, spark, arcing, burning or breakdown	AEC-Q200-002 Human body, 8KV.
Insulation Resistance	Over 100 M Ω on Overcoat layer face up	JIS-C-5201-1 4.6 100V _{DC} for 60 +10/-0 seconds
Voltage Proof	$\triangle R$: \pm 1% Without damage by flashover, spark, arcing, burning or breakdown	JIS-C-5201-1 4.7 400V _{AC} (rms.) for 60 +10/ -0 seconds

Mechanical

Item	Specification and Requirement	Test Method
Solderability	The surface of terminal immersed shall be minimum of 95% covered with a new coating of solder	J-STD-002 Method B category 3 245±5°C for 5±0.5 seconds.
Resistance to Solder Heat	\triangle R: \pm 0.5% Without distinct damage in appearance	MIL-STD-202 Method 210 $260 \pm 5^{\circ}\text{C for } 10 \pm 1 \text{ seconds}.$
Board Flex	\triangle R: \pm 1.0% Without mechanical damage such as break.	AEC-Q200-005 Bending value: 2 mm for 60 ± 1 seconds.
Vibration	\triangle R: \pm 0.5% Without distinct damage in appearance	MIL-STD-202 Method 204 5G's for 20 minutes, 12 cycles each of 3 orientations. Test from 10- 2000Hz.

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Mechanical Shock	\triangle R: \pm 0.5% Without distinct damage in appearance	MIL-STD-202 Method 213 100G's peak value, 6ms, Half-sine waveform, 12.3ft/sec.
Terminal Strength (SMD)	\triangle R: \pm 1% Without mechanical damage such as break.	AEC-Q200-006 Force of 1.8Kg for 60 seconds.

Endurance

Item	Specification and Requirement	Test Method
		JESD22 Method JA-104
Tomporature Cycling	△R: ± 0.5%	-55°C to 150°C /1000cycle
Temperature Cycling	Without distinct damage in appearance	30 min maximum dwell time at each
		temperature on FR4(PCB).
	△R: ± 0.5%	MIL-STD-202 Method 103
Biased Humidity		1000 hours, 85°C /85%R.H,
	Without distinct damage in appearance	applied for 10% rated power.
		MIL-STD-202 Method 108
Operational Life	△R: ± 1.0%	70°C, 100% rated power
Operational Life	Without distinct damage in appearance	1.5 hours ON, 0.5 hours Off
		For total 1000 hours
High Temperature Storage	$\triangle R$: \pm 1.0% Without distinct damage in appearance	MIL-STD-202 Method 108 170°C for 1000 hours.
Moisture Resistance	$\triangle R$: \pm 0.5% Without distinct damage in appearance	MIL-STD-202 Method 106 65°C /90-100%RH, unpowered, 7b not required

Note : Measurement at 24 \pm 4 hours after test conclusion for all reliability tests-parts.

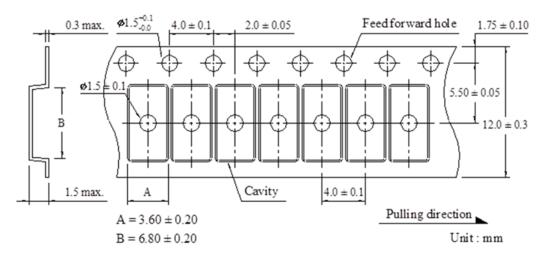
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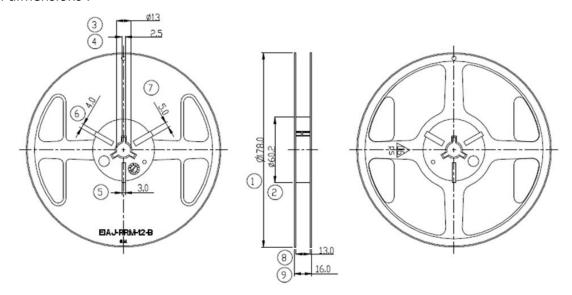


PACKAGING DESCRIPTIONS:

Dimensions:



Reel dimensions:



Unit:mm

Symbol	1	2	3	4	5	6	7	8	9
Size	178.0	60.2	13.0	2.5	3.0	4.0	5.0	13.0	16.0
3126	±1	±0.5	±0.5	+0.5/-0	+0.5/-0	+0.5/-0	+0.5/-0	±0.5	±0.15

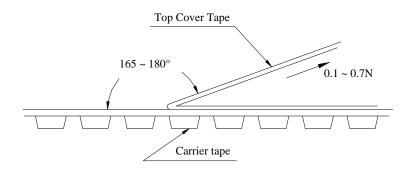
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Peel Strength of Top Cover Tape:

The peel speed shall be about 300mm/min and the peel force of top cover tape shall between 0.1 to 0.7N



Number of Taping:

2,000 pieces / reel

Label Marking:

The following items shall be marked on tray

- (1) Description
- (2) Quantity
- (3) Part No.
- (4) Tapping No.

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Care Note:

Care note for storage

- (1) Chip resistor shall be stored in a room where temperature and humidity must be controlled. (temperature 5 to 35°C, humidity < 60% RH) However, a humidity keep it low, as it is possible.
- (3) Chip resistor shall be stored as direct sunshine doesn't hit on it.
- (4) Chip resistor shall be stored with no moisture, dust, a material that will make solderability inferior, and a harmful gas (Chloridation hydrogen, sulfurous acid gas, and sulfuration hydrogen)

Care note for operating and handling

- (1) Protect the edge and coating of the sensors from mechanical stress.
- (2) Avoid bending of printing circuit board (PCB) when cutting and fixing it on support body to reduce mechanical stress on sensors.
- (3) Sensor should be used within the condition of specification.
 Note: When a voltage higher than specified value is loaded to the sensor, this may damage the sensor material due to temperature rise.
- (4) The loaded voltage should consult terminal temperature of the sensor according to the derating curve.
- (5) When applying a high current exceeding suggested specification (pulse current, shock current) to the sensor, it is necessary to re-evaluate the operating condition before using it in the system.

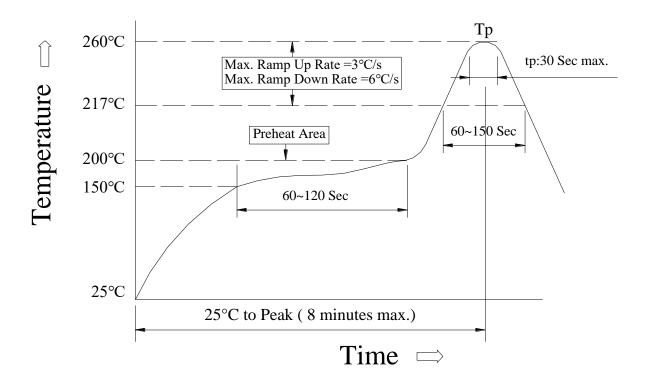
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Reflow profile:

Recommended Reflow Profile



(1) Reflow Soldering Method:

Reflow Soldering	Tp:255~260°C	Max.30 seconds (tp)
	217°C	60~150 seconds
Pre-Heat	150 ~ 200°C	60~120 seconds
Time 25°C to peak temperature	8 minutes max.	

Reference: JEDEC J-STD-020E

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